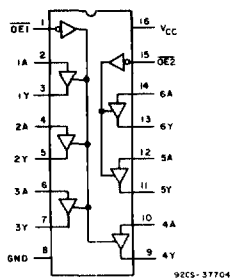


File Number 1538

Advance Information/
Preliminary Data**CD54/74HC367, CD54/74HCT367
CD54/74HC368, CD54/74HCT368****High-Speed CMOS Logic****FUNCTIONAL DIAGRAM****CD54/74HC367, HCT367****Hex Buffer/Line Driver, 3-State**

Non-Inverting and Inverting

Type Features:

- Buffered inputs
- High current bus driver outputs
- Two independent 3-state enable controls
- Typical propagation delay $t_{PHL}, t_{PLH} = 8 \text{ ns}$ @ $V_{CC} = 5 \text{ V}$, $C_L = 15 \text{ pF}$

The RCA-CD54/74HC367, 368 and CD54/74HCT367, 368 silicon gate CMOS 3-state buffers are general-purpose high-speed non-inverting and inverting buffers. They have high drive current outputs which enable high-speed operation even when driving large bus capacitances. These circuits possess the low power dissipation of CMOS circuitry, yet have speeds comparable to low power Schottky TTL circuits. Both circuits are capable of driving up to 15 low power Schottky inputs.

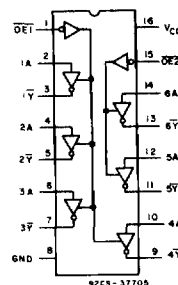
The CD54/74HC, HCT367 are non-inverting buffers, whereas the CD54/74HC, HCT368 are inverting buffers. These devices have two output enables, one enable (OE1) controls 4 gates and the other (OE2) controls the remaining 2 gates.

The CD54/74HCT367 and CD54/74HCT368 logic families are speed, function, and pin compatible with the standard 54LS/74LS logic family.

The CD54HC367 and CD54HCT367 are supplied in 16-lead hermetic dual-in-line ceramic packages (F suffix). The CD74HC367 and CD74HCT367 are in 16-lead dual-in-line plastic packages (E suffix), also in 16-lead dual-in-line surface mount plastic packages (M suffix). Both types are also available in chip form (H suffix).

Family Features:

- Fanout (Over Temperature Range):
Standard Outputs - 10 LSTTL Loads
Bus Driver Outputs - 15 LSTTL Loads
- Wide Operating Temperature Range:
CD74HC/HCT: -40 to +85°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- Alternate Source is Philips/Signetics
- CD54HC/CD74HC Types:
2 to 6 V Operation
High Noise Immunity:
 $N_{IL} = 30\%$, $N_{IH} = 30\%$; @ $V_{CC} = 5 \text{ V}$
- CD54HCT/CD74HCT Types:
4.5 to 5.5 V Operation
Direct LSTTL Input Logic Compatibility
 $V_{IL} = 0.8 \text{ V Max.}$, $V_{IH} = 2 \text{ V Min.}$
CMOS Input Compatibility
 $I_{IL}, I_{IH} \leq 1 \mu\text{A}$ @ V_{OL}, V_{OH}

FUNCTIONAL DIAGRAM**CD54/74HC368, HCT368**

CD54/74HC367, CD54/74HCT367 CD54/74HC368, CD54/74HCT368

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE, (V_{cc}):	
(Voltages referenced to ground)	-0.5 to + 7 V
DC INPUT DIODE CURRENT, I_{ik} (FOR $V_i < -0.5$ V OR $V_i > V_{cc} + 0.5$ V)	± 20 mA
DC OUTPUT DIODE CURRENT, I_{ok} (FOR $V_o < -0.5$ V OR $V_o > V_{cc} + 0.5$ V)	± 20 mA
DC DRAIN CURRENT, PER OUTPUT (I_o) (FOR -0.5 V $< V_o < V_{cc} + 0.5$ V)	± 35 mA
DC V_{cc} OR GROUND CURRENT (I_{cc})	± 70 mA
POWER DISSIPATION PER PACKAGE (P_D):	
For $T_A = -40$ to $+60^\circ\text{C}$ (PACKAGE TYPE E)	500 mW
For $T_A = -60$ to -85°C (PACKAGE TYPE E)	Derate Linearly at 8 mW/ $^\circ\text{C}$ to 300 mW
For $T_A = -55$ to -100°C (PACKAGE TYPE F, H)	500 mW
For $T_A = +100$ to -125°C (PACKAGE TYPE F, H)	Derate Linearly at 8 mW/ $^\circ\text{C}$ to 300 mW
For $T_A = -40$ to $+70^\circ\text{C}$ (PACKAGE TYPE M)	400 mW
For $T_A = +70$ to $+125^\circ\text{C}$ (PACKAGE TYPE M)	Derate Linearly at 6 mW/ $^\circ\text{C}$ to 70 mW
OPERATING TEMPERATURE RANGE (T_A)	
PACKAGE TYPE F, H	-55 to $+125^\circ\text{C}$
PACKAGE TYPE E, M	-40 to $+85^\circ\text{C}$
STORAGE TEMPERATURE (T_{stg})	-65 to $+150^\circ\text{C}$
LEAD TEMPERATURE (DURING SOLDERING):	
At distance $1/16 \pm 1/32$ in. (1.59 ± 0.79 mm) from case for 10 s max	-265°C
Unit inserted into a PC Board (min. thickness $1/16$ in., 1.59 mm) with solder contacting lead tips only	$+300^\circ\text{C}$

TRUTH TABLES

Inputs		Outputs
$\overline{OE}$	A	Y
L	L	L
L	H	H
H	X	(Z)

CD54/74HC, HCT367

Inputs		Outputs
$\overline{OE}$	A	Y
L	L	H
L	H	L
H	X	(Z)

CD54/74HC, HCT368

L = LOW voltage level.
H = HIGH voltage level.
X = Don't care.
(Z) = High impedance (off) state.

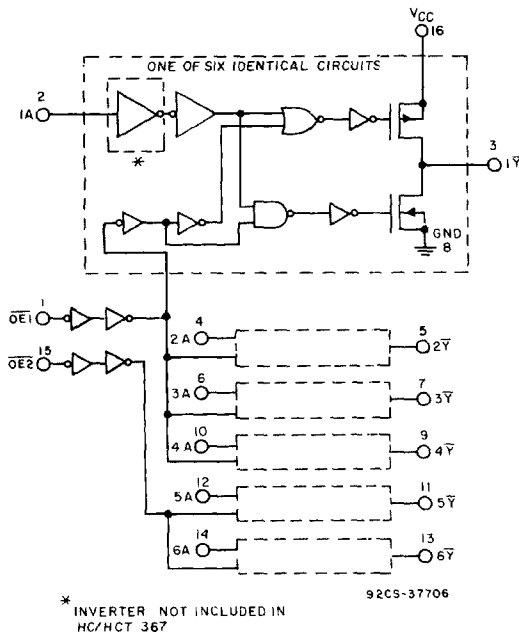


Fig. 1 - Logic diagram for HC/HCT367 and HC/HCT368.
(Outputs for HC/HCT367 are complements of those shown, i.e., 1Y, 2Y, etc.).

CD54/74HC367, CD54/74HCT367

CD54/74HC368, CD54/74HCT368

STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTICS		CD74HC367/368/CD54HC367/368										CD74HCT367/368/CD54HCT367/368										UNITS
		TEST CONDITIONS			74HC/54HC TYPE			74HC TYPE		54HC TYPE		TEST CONDITIONS			74HCT/54HCT TYPE			74HCT TYPE		54HCT TYPE		
		V_i V	I_o mA	V_{CC} V	+25°C			-40/ +85°C		-55/ +125°C		V_i V	V_{CC} V	+25°C			-40/ +85°C		-55/ +125°C			
Min	Typ	Max	Min	Max	Min	Max	V_i V	V_{CC} V	Min	Typ	Max	Min	Max	Min	Max							
High-Level Input Voltage	V_{IH}		2	1.5	—	—	1.5	—	1.5	—	—	4.5	2	—	—	2	—	2	—	V		
			4.5	3.15	—	—	3.15	—	3.15	—	—	to	—	—	0.8	—	0.8	—	0.8	V		
			6	4.2	—	—	4.2	—	4.2	—	—	5.5	—	—	—	—	—	—	—	V		
Low-Level Input Voltage	V_{IL}		2	—	—	0.5	—	0.5	—	0.5	—	4.5	—	—	0.8	—	0.8	—	0.8	V		
			4.5	—	—	1.35	—	1.35	—	1.35	—	to	—	—	—	—	—	—	—	V		
			6	—	—	1.8	—	1.8	—	1.8	—	5.5	—	—	—	—	—	—	—	V		
High-Level Output Voltage	V_{OH}	V_{IL} or V_{IH}	-0.02	2	1.9	—	—	1.9	—	1.9	—	V_{IL} or V_{IH}	4.5	4.4	—	—	4.4	—	4.4	—	V	
CMOS Loads				4.5	4.4	—	—	4.4	—	4.4	—											
				6	5.9	—	—	5.9	—	5.9	—											
TTL Loads (Bus Driver)		V_{IL} or V_{IH}	-6 -7.8	4.5	3.98	—	—	3.84	—	3.7	—	V_{IL} or V_{IH}	4.5	3.98	—	—	3.84	—	3.7	—	V	
				6	5.48	—	—	5.34	—	5.2	—											
Low-Level Output Voltage	V_{OL}	V_{IL} or V_{IH}	0.02	2	—	—	0.1	—	0.1	—	0.1	V_{IL} or V_{IH}	4.5	—	—	0.1	—	0.1	—	0.1	V	
CMOS Loads				4.5	—	—	0.1	—	0.1	—	0.1											
				6	—	—	0.1	—	0.1	—	0.1											
TTL Loads (Bus Driver)		V_{IL} or V_{IH}	6 7.8	4.5	—	—	0.26	—	0.33	—	0.4	V_{IL} or V_{IH}	4.5	—	—	0.26	—	0.33	—	0.4	V	
				6	—	—	0.26	—	0.33	—	0.4											
Input Leakage Current	I_i	V_{CC} or Gnd	6	—	—	±0.1	—	±1	—	±1	—	Any Voltage Between V_{CC} and Gnd	5.5	—	—	±0.1	—	±1	—	±1	μA	
Quiescent Device Current	I_{CC}	V_{CC} or Gnd	0	6	—	—	8	—	80	—	160	V_{CC} or Gnd	5.5	—	—	8	—	80	—	160	μA	
Additional Quiescent Device Current per Input Pin: 1 Unit Load	ΔI_{CC}^*											$V_{CC}-2.1$	4.5 to 5.5	—	100	360	—	450	—	490	μA	
3-State Leakage Current	I_{OZ}	V_{IL} or V_{IH}	$V_O = V_{CC}$ or Gnd	6	—	—	±0.5	—	±5	—	±10	V_{IL} or V_{IH}	5.5	—	—	±0.5	—	±5	—	±10	μA	

*For dual-supply systems theoretical worst case ($V_i = 2.4$ V, $V_{cc} = 5.5$ V) specification is 1.8 mA.

HCT INPUT LOADING TABLE

INPUT	UNIT LOADS*
OE1	0.6
ALL OTHERS	0.55

*Unit Load is ΔI_{cc} limit specified in Static Characteristic Chart, e.g., 360 μA max. @ 25°C.

CD54/74HC367, CD54/74HCT367 CD54/74HC368, CD54/74HCT368

RECOMMENDED OPERATING CONDITIONS:

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIMITS		UNITS
	MIN.	MAX.	
Supply-Voltage Range (For T_A =Full Package Temperature Range) V_{CC}^*			
CD54/74HC Types	2	6	V
CD54/74HCT Types	4.5	5.5	
DC Input or Output Voltage V_i, V_o	0	V_{CC}	V
Operating Temperature T_A :			
CD74 Types	-40	+85	°C
CD54 Types	-55	+125	
Input Rise and Fall Times t_r, t_f			
at 2 V	0	1000	ns
at 4.5 V	0	500	
at 6 V	0	400	

*Unless otherwise specified, all voltages are referenced to Ground.

SWITCHING CHARACTERISTICS ($V_{CC}=5$ V, $C_L=15$ pF, $T_A=25^\circ$ C, Input $t_r, t_f=6$ ns)

CHARACTERISTIC	SYMBOL	TYPICAL				UNITS
		367		368		
		HC	HCT	HC	HCT	
Propagation Delay	t_{PHL}	8	9	9	11	ns
Data to Output	t_{PLH}					
Output Enable and Disable to Outputs	$t_{PZH}, t_{PZL}, t_{PHZ}, t_{PLZ}$	12	14	12	14	ns
Power Dissipation Capacitance *	C_{PD}	40	42	40	42	pF

* C_{PD} is used to determine the dynamic power consumption, per buffer.

$PD = V_{CC}^2 f_i (C_{PD} + C_L)$ where:

f_i = input frequency

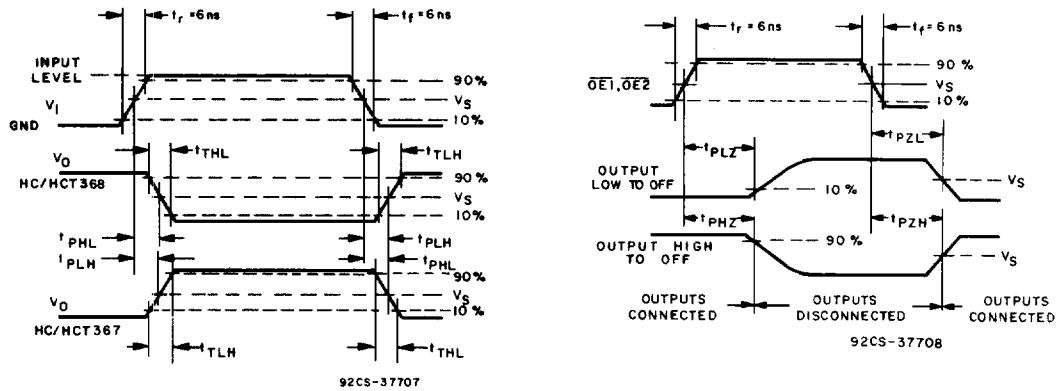
C_L = output load capacitance

V_{CC} = supply voltage

SWITCHING CHARACTERISTICS ($C_L=50$ pF, Input $t_r, t_f=6$ ns)

CHARACTERISTIC	SYMBOL	V _{CC}	25° C				-40° C to +85° C				-55° C to +125° C				UNITS
			HC		HCT		74HC		74HCT		54HC		54HCT		
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Propagation Delay	t _{PLH}	2	—	105	—	—	—	130	—	—	—	160	—	—	ns
Data to Outputs	t _{PHL}	4.5	—	21	—	25	—	26	—	31	—	32	—	38	
HC/HCT367		6	—	18	—	—	—	24	—	—	—	27	—	—	
Propagation Delay	t _{PLH}	2	—	105	—	—	—	130	—	—	—	160	—	—	ns
Data to Outputs	t _{PHL}	4.5	—	21	—	30	—	26	—	38	—	32	—	45	
HC/HCT368		6	—	18	—	—	—	24	—	—	—	27	—	—	
Propagation Delay	t _{PZH} , t _{PZL}	2	—	150	—	—	—	190	—	—	—	225	—	—	ns
Output Enable & Disable	t _{PHZ} , t _{PLZ}	4.5	—	30	—	35	—	38	—	44	—	45	—	53	
to Outputs		6	—	26	—	—	—	33	—	—	—	38	—	—	
Output Transition	t _{TLH}	2	—	60	—	—	—	75	—	—	—	90	—	—	ns
Time	t _{THL}	4.5	—	12	—	12	—	15	—	15	—	18	—	18	
		6	—	10	—	—	—	13	—	—	—	15	—	—	
Input Capacitance	C _i		—	10	—	10	—	10	—	10	—	10	—	10	pF
3-State Output Capacitance	C _o		—	20	—	20	—	20	—	20	—	20	—	20	pF

CD54/74HC367, CD54/74HCT367 CD54/74HC368, CD54/74HCT368



Input Level	54/74HC	54/74HCT
	V_{CC}	3 V
Switching Voltage, V_S	50% V_{CC}	1.3 V

Fig. 2 - Transition times and propagation delay times.

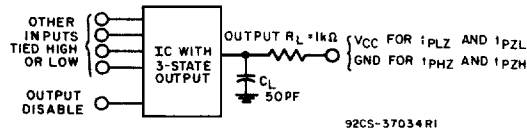


Fig. 3 - Three-state propagation delay test circuit.